

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ifw 2827

Applicant: Biju Chandran et al.

Title: SEMICONDUCTOR PACKAGE WITH PACKAGE-TO-DIE INTERCONNECT SCHEME (As Amended)

Docket No.: 884.B14US1

Filed: December 21, 2001

Examiner: James M. Mitchell



Serial No.: 10/023723

Due Date: June 29, 2004

Group Art Unit: 2827

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ An Amendment and Response Under 37 C.F.R. 1.111 (13 Pages).
- ☒ Authorization to charge Deposit Account No. 19-0743 in the amount of \$90.00 to cover the fee for additional claims as calculated below.

If not provided for in a separate paper filed herewith, If an additional fee is required due to changes to the claims, the fee has been calculated as follows:

CLAIMS AS AMENDED						
	(1) Claims Remaining After Amendment		(2) Highest Number Previously Paid For	(3) Present Extra	Rate	Fee
TOTAL CLAIMS	31	-	26	5	x 18.00 =	\$90.00
INDEPENDENT CLAIMS	4	-	4	0	x 86.00 =	\$0.00
MULTIPLE DEPENDENT CLAIMS PRESENTED						\$0.00
TOTAL						\$90.00

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

By: Ann M. McCrackin
Atty: Ann M. McCrackin
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 1st day of June, 2004.

KACIA LEE
Name

Kacia Lee
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)



S/N 10/023723

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Biju Chandran et al.	Examiner:	James M. Mitchell
Serial No.:	10/023723	Group Art Unit:	2827
Filed:	December 21, 2001	Docket No.:	884.B14US1
Title:	SEMICONDUCTOR PACKAGE WITH PACKAGE-TO-DIE INTERCONNECT SCHEME (As Amended)		
Assignee:	Intel Corporation	Customer No:	21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on March 29, 2004. Please amend the above-identified patent application as follows.

06/07/2004 MGE BREM1 00000123 190743 10023723

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